Power MOSFET

60 V, 295 mA, Dual N–Channel with ESD Protection, SC–88

Features

- Low R_{DS(on)}
- Low Gate Threshold
- Low Input Capacitance
- ESD Protected Gate
- This is a Pb–Free Device

Applications

- Low Side Load Switch
- DC–DC Converters (Buck and Boost Circuits)

MAXIMUM RATINGS (T_J = $25^{\circ}C$ unless otherwise stated)

· · · · · · · · · · · · · · · · · · ·						
Parame	Symbol	Value	Units			
Drain-to-Source Voltage	V _{DSS}	60	V			
Gate-to-Source Voltage			V _{GS}	±20	V	
Continuous Drain	Steady	$T_A = 25^{\circ}C$	۱ _D	295	mA	
Current (Note 1)	State	$T_A = 85^{\circ}C$		212		
	t ≤ 5 s	$T_A = 25^{\circ}C$	1	304		
		$T_A = 85^{\circ}C$	1	219		
Power Dissipation (Note 1)	Steady State	$T_A = 25^{\circ}C$	P _D	250	mW	
	t ≤ 5 s			266		
Pulsed Drain Current	t _p =	= 10 μs	I _{DM}	900	mA	
Operating Junction and Storage Temperature			T _J , T _{STG}	–55 to 150	°C	
Source Current (Body Diode)		۱ _S	210	mA		
Lead Temperature for Soldering Purposes (1/8" from case for 10 s)		ΤL	260	°C		
Gate–Source ESD Rating (HBM, Method 3015)			ESD	1400	V	

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

THERMAL RESISTANCE RATINGS

Parameter	Symbol	Value	Units
Junction-to-Ambient - Steady State	$R_{\theta JA}$	500	°C/W
Junction-to-Ambient – t \leq 5 s	$R_{\theta J A}$	470	

1. Surface mounted on FR4 board using 1 in sq pad size (Cu area = 1.127 in sq [2 oz] including traces).

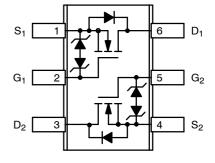


ON Semiconductor®

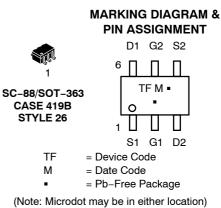
http://onsemi.com

V _{(BR)DSS}	R _{DS(on)} MAX	I _D Max
60 V	1.6 Ω @ 10 V	295 mA
	2.5 Ω @ 4.5 V	293 1114





Top View



ORDERING INFORMATION

Device	Package	Shipping [†]
NTJD5121NT1G	SC-88 (Pb-Free)	3000 / Tape & Reel
NTJD5121NT2G	SC-88 (Pb-Free)	3000 / Tape & Reel

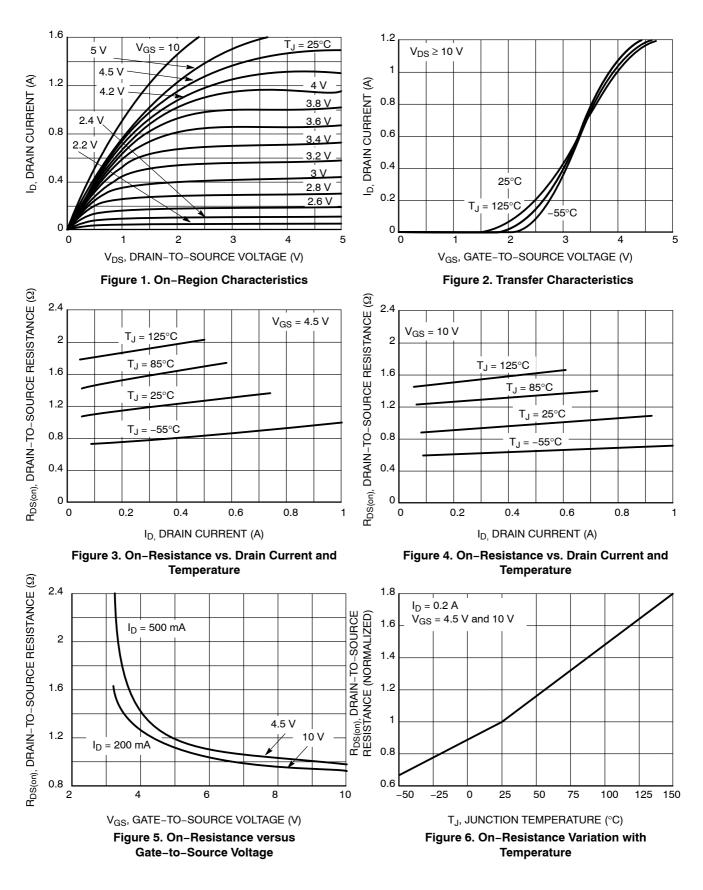
+ For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

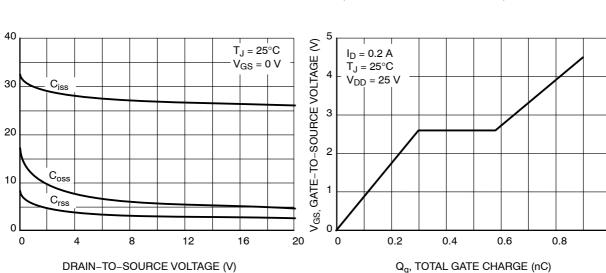
ELECTRICAL CHARACTERISTICS (T_J = 25° C unless otherwise stated)

Parameter	Symbol	Test Condition		Min	Тур	Мах	Unit
OFF CHARACTERISTICS	· · · · ·				-	-	-
Drain-to-Source Breakdown Voltage	V _{(BR)DSS}	V_{GS} = 0 V, I _D = 250 µA		60			V
Drain-to-Source Breakdown Voltage Temperature Coefficient	V _{(BR)DSS} /T _J	I _D = 250 μA, r	ef to 25°C		92		mV/°C
Zero Gate Voltage Drain Current	I _{DSS} V _{GS} = 0 V,		$T_J = 25^{\circ}C$			1.0	μΑ
		$V_{\rm DS} = 60 \rm V$	T _J = 125°C			500	
Gate-to-Source Leakage Current	I _{GSS}	V _{DS} = 0 V, V _C	_{as} = ±20 V			±10	μA
ON CHARACTERISTICS (Note 2)	•						-
Gate Threshold Voltage	V _{GS(TH)}	$V_{GS} = V_{DS}, I_{DS}$	o = 250 μA	1.0	1.7	2.5	V
Negative Threshold Temperature Coefficient	V _{GS(TH)} /T _J				4.0		mV/°C
Drain-to-Source On Resistance	R _{DS(on)}	V _{GS} = 10 V, I _D = 500 mA			1.0	1.6	Ω
		V _{GS} = 4.5 V, I _[V _{GS} = 4.5 V, I _D = 200 mA		1.2	2.5	
Forward Transconductance	9 _{FS}	V _{DS} = 5 V, I _D = 200 mA			80		S
CHARGES AND CAPACITANCES	•						-
Input Capacitance	C _{ISS}	V _{GS} = 0 V, f = 1.0 MHz, V _{DS} = 20 V			26		pF
Output Capacitance	C _{OSS}				4.4		
Reverse Transfer Capacitance	C _{RSS}				2.5		
Total Gate Charge	Q _{G(TOT)}				0.9		nC
Threshold Gate Charge	Q _{G(TH)}	V _{GS} = 4.5 V, V	ν _{DS} = 25 V,		0.2		1
Gate-to-Source Charge	Q _{GS}	$I_D = 200$) mA		0.3		
Gate-to-Drain Charge	Q _{GD}		Ē		0.28		
SWITCHING CHARACTERISTICS (No	ote 3)						-
Turn-On Delay Time	t _{d(on)}				22		ns
Rise Time	t _r	V_{GS} = 4.5 V, V_{DD} = 25 V, I _D = 200 mA, R _G = 25 Ω			34		
Turn-Off Delay Time	t _{d(off)}				34		1
Fall Time	t _f				32		1
DRAIN-SOURCE DIODE CHARACTE	RISTICS						
Forward Diode Voltage	V _{SD}	V _{GS} = 0 V,	$T_J = 25^{\circ}C$		0.8	1.2	V
		$I_{\rm S} = 200 \text{ mA}$ $T_{\rm J} = 85^{\circ}\text{C}$			0.7		-

Pulse Test: pulse width ≤ 300 μs, duty cycle ≤ 2%.
Switching characteristics are independent of operating junction temperatures.

TYPICAL PERFORMANCE CURVES (T_J = 25°C unless otherwise noted)





TYPICAL PERFORMANCE CURVES (T_J = 25°C unless otherwise noted)



C, CAPACITANCE (pF)

Figure 8. Gate-to-Source and Drain-to-Source Voltage vs. Total Charge

1

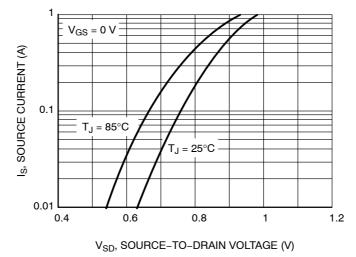
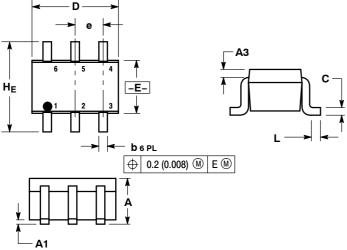


Figure 9. Diode Forward Voltage vs. Current

PACKAGE DIMENSIONS

SC-88/SC70-6/SOT-363 CASE 419B-02 **ISSUE W**



NOTES: DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

CONTROLLING DIMENSION: INCH. 419B-01 OBSOLETE, NEW STANDARD 419B-02. 2.

3

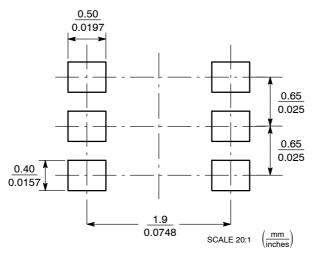
	MILLIMETERS			INCHES			
DIM	MIN	NOM	MAX	MIN	NOM	MAX	
Α	0.80	0.95	1.10	0.031	0.037	0.043	
A1	0.00	0.05	0.10	0.000	0.002	0.004	
A3	0.20 REF			(0.008 RI	EF	
b	0.10	0.21	0.30	0.004	0.008	0.012	
С	0.10	0.14	0.25	0.004	0.005	0.010	
D	1.80	2.00	2.20	0.070	0.078	0.086	
Е	1.15	1.25	1.35	0.045	0.049	0.053	
е	0.65 BSC			0.026 BSC			
L	0.10	0.20	0.30	0.004	0.008	0.012	
HE	2.00	2.10	2.20	0.078	0.082	0.086	

STYLE 26: PIN 1. SOURCE 1 2. GATE 1 3. DRAIN 2

4. SOURCE 2 5. GATE 2

6. DRAIN 1

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

ON Semiconductor and 💷 are registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All or operating parameters, including "Typical" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor P.O. Box 5163, Denver, Colorado 80217 USA Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada Email: orderlit@onsemi.com

N. American Technical Support: 800-282-9855 Toll Free USA/Canada Europe, Middle East and Africa Technical Support:

Phone: 421 33 790 2910 Japan Customer Focus Center Phone: 81-3-5817-1050

ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative